



**MOTOROLA**

**MC14000UB**

### DUAL 3-INPUT "NOR" GATE PLUS INVERTER

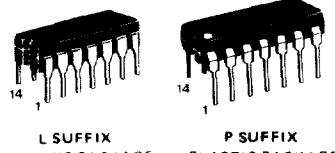
The MC14000UB dual 3-input NOR gate plus inverter is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. These complementary MOS logic gates find primary use where low power dissipation and/or high noise immunity is desired.

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Logic Swing Independent of Fanout
- Pin-for-Pin Replacement for CD4000UB

### CMOS SSI

(LOW POWER COMPLEMENTARY MOS)

### DUAL 3-INPUT "NOR" GATE PLUS INVERTER



#### ORDERING INFORMATION

A Series: -55°C to +125°C  
MC14XXXUBAL (Ceramic Package Only)

C Series: -40°C to +85°C  
MC14XXXUBCP (Plastic Package)  
MC14XXXUBCL (Ceramic Package)

#### MAXIMUM RATINGS\* (Voltages Referenced to V<sub>SS</sub>)

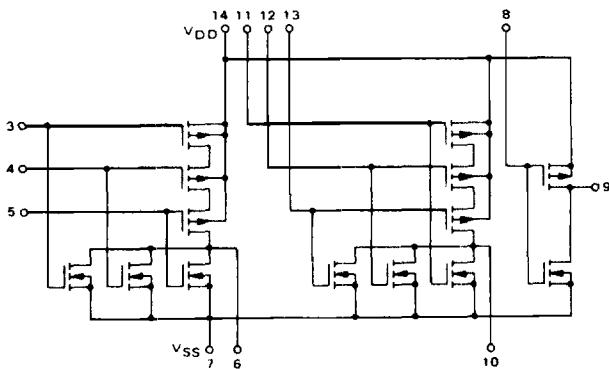
Symbol	Parameter	Value	Unit
V <sub>DD</sub>	DC Supply Voltage	-0.5 to +18.0	V
V <sub>in</sub> , V <sub>out</sub>	Input or Output Voltage (DC or Transient)	-0.5 to V <sub>DD</sub> + 0.5	V
I <sub>in</sub> , I <sub>out</sub>	Input or Output Current (DC or Transient), per Pin	±10	mA
P <sub>D</sub>	Power Dissipation, per Package†	500	mW
T <sub>stg</sub>	Storage Temperature	-65 to +150	°C
T <sub>L</sub>	Lead Temperature (8-Second Soldering)	260	°C

\*Maximum Ratings are those values beyond which damage to the device may occur.

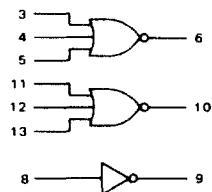
†Temperature Derating: Plastic "P" Package - 12mW/°C from 65°C to 85°C  
Ceramic "L" Package - 12mW/°C from 100°C to 125°C

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#### CIRCUIT SCHEMATIC



#### LOGIC DIAGRAM



V<sub>DD</sub> = Pin 14  
V<sub>SS</sub> = Pin 7

#### PIN ASSIGNMENT

1	NC	V <sub>DD</sub>	14
2	NC	In 3 <sub>B</sub>	13
3	In 1 <sub>A</sub>	In 2 <sub>B</sub>	12
4	In 2 <sub>A</sub>	In 1 <sub>B</sub>	11
5	In 3 <sub>A</sub>	Out <sub>B</sub>	10
6	Out <sub>A</sub>	Out <sub>C</sub>	9
7	V <sub>SS</sub>	In 1 <sub>C</sub>	8

NC = NO CONNECTION

# MC14000UB

## ELECTRICAL CHARACTERISTICS (Voltages Referenced to V<sub>SS</sub>)

Characteristic	Symbol	V <sub>DD</sub> Vdc	T <sub>low</sub> *		25°C				T <sub>high</sub> *		Unit	
			Min	Max	Min	Typ #	Max	Min	Max	Min		
Output Voltage V <sub>in</sub> = V <sub>DD</sub> or 0	V <sub>OL</sub>	5.0	—	0.05	—	0	0.05	—	0.05	—	Vdc	
		10	—	0.05	—	0	0.05	—	0.05	—	Vdc	
		15	—	0.05	—	0	0.05	—	0.05	—	Vdc	
	V <sub>OH</sub>	5.0	4.95	—	4.95	5.0	—	4.95	—	—	Vdc	
		10	9.95	—	9.95	10	—	9.95	—	—	Vdc	
		15	14.95	—	14.95	15	—	14.95	—	—	Vdc	
Input Voltage (V <sub>O</sub> = 4.5 Vdc) (V <sub>O</sub> = 9.0 Vdc) (V <sub>O</sub> = 13.5 Vdc)	V <sub>IL</sub>	5.0	—	1.0	—	2.25	1.0	—	1.0	—	Vdc	
		10	—	2.0	—	4.50	2.0	—	2.0	—	Vdc	
		15	—	2.5	—	6.75	2.5	—	2.5	—	Vdc	
	V <sub>IH</sub>	5.0	4.0	—	4.0	2.75	—	4.0	—	—	Vdc	
		10	8.0	—	8.0	5.50	—	8.0	—	—	Vdc	
		15	12.5	—	12.5	8.25	—	12.5	—	—	Vdc	
Output Drive Current (AL Device) (V <sub>OH</sub> = 2.5 Vdc) (V <sub>OH</sub> = 4.6 Vdc) (V <sub>OH</sub> = 9.5 Vdc) (V <sub>OH</sub> = 13.5 Vdc)	Source	I <sub>OH</sub>	5.0	-1.2	—	-1.0	-1.7	—	-0.7	—	mAdc	
		I <sub>OH</sub>	5.0	-0.25	—	-0.2	-0.36	—	-0.14	—	mAdc	
		I <sub>OH</sub>	10	-0.62	—	-0.5	-0.9	—	-0.35	—	mAdc	
		I <sub>OH</sub>	15	-1.8	—	-1.5	-3.5	—	-1.1	—	mAdc	
	Sink	I <sub>OL</sub>	5.0	0.64	—	0.51	0.88	—	0.36	—	mAdc	
		I <sub>OL</sub>	10	1.6	—	1.3	2.25	—	0.9	—	mAdc	
Output Drive Current (CL/CP Device) (V <sub>OH</sub> = 2.5 Vdc) (V <sub>OH</sub> = 4.6 Vdc) (V <sub>OH</sub> = 9.5 Vdc) (V <sub>OH</sub> = 13.5 Vdc)	Source	I <sub>OH</sub>	5.0	-1.0	—	-0.8	-1.7	—	-0.6	—	mAdc	
		I <sub>OH</sub>	5.0	-0.2	—	-0.16	-0.36	—	-0.12	—	mAdc	
		I <sub>OH</sub>	10	-0.5	—	-0.4	-0.9	—	-0.3	—	mAdc	
		I <sub>OH</sub>	15	-1.4	—	-1.2	-3.5	—	-1.0	—	mAdc	
	Sink	I <sub>OL</sub>	5.0	0.52	—	0.44	0.88	—	0.36	—	mAdc	
		I <sub>OL</sub>	10	1.3	—	1.1	2.25	—	0.9	—	mAdc	
Input Current (AL Device)	I <sub>IN</sub>	15	—	±0.1	—	±0.00001	±0.1	—	±1.0	—	μAdc	
	I <sub>IN</sub>	15	—	±0.3	—	±0.00001	±0.3	—	±1.0	—	μAdc	
	C <sub>IN</sub>	—	—	—	—	5.0	7.5	—	—	—	pF	
	Quiescent Current (AL Device) (Per Package)	I <sub>DD</sub>	5.0	—	0.25	—	0.0005	0.25	—	7.5	μAdc	
	Quiescent Current (CL/CP Device) (Per Package)	I <sub>DD</sub>	10	—	0.5	—	0.0010	0.5	—	15	μAdc	
		I <sub>DD</sub>	15	—	1.0	—	0.0015	1.0	—	30	μAdc	
Total Supply Current**† (Dynamic plus Quiescent, Per Gate, C <sub>L</sub> = 50 pF)	I <sub>T</sub>	5.0	I <sub>T</sub> = (0.3 μA/kHz) f + I <sub>DD</sub> N				I <sub>T</sub> = (0.6 μA/kHz) f + I <sub>DD</sub> N				μAdc	
	I <sub>T</sub>	10	I <sub>T</sub> = (0.6 μA/kHz) f + I <sub>DD</sub> N				I <sub>T</sub> = (0.8 μA/kHz) f + I <sub>DD</sub> N					
	I <sub>T</sub>	15	I <sub>T</sub> = (0.8 μA/kHz) f + I <sub>DD</sub> N				I <sub>T</sub> = (1.0 μA/kHz) f + I <sub>DD</sub> N					

\*T<sub>low</sub> = 55°C for AL Device, -40°C for CL/CP Device.

†T<sub>high</sub> = +125°C for AL Device, +85°C for CL/CP Device.

#Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

\*\*The formulas given are for the typical characteristics only at 25°C.

†To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) VfK$$

where: I<sub>T</sub> is in μA (per package), C<sub>L</sub> in pF, V = (V<sub>DD</sub> - V<sub>SS</sub>) in volts, f in kHz is input frequency, and K = 0.001 × the number of exercised gates per package.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V<sub>in</sub> and V<sub>out</sub> should be constrained to the range V<sub>SS</sub> ≤ (V<sub>in</sub> or V<sub>out</sub>) ≤ V<sub>DD</sub>. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V<sub>SS</sub> or V<sub>DD</sub>). Unused outputs must be left open.

# MC14000UB

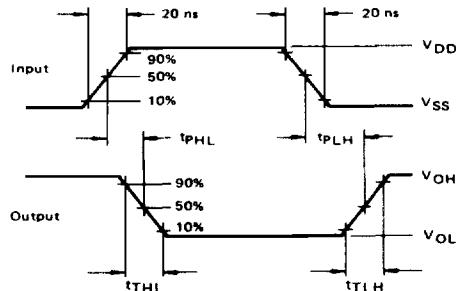
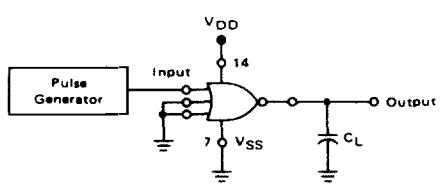
**SWITCHING CHARACTERISTICS\*** ( $C_L = 50 \text{ pF}$ ,  $T_A = 25^\circ\text{C}$ )

Characteristic	Symbol	$V_{DD}$ Vdc	Min	Typ #	Max	Unit
Output Rise Time $t_{TLH} = (3.0 \text{ ns/pF}) C_L + 30 \text{ ns}$ $t_{TLH} = (1.5 \text{ ns/pF}) C_L + 15 \text{ ns}$ $t_{TLH} = (1.1 \text{ ns/pF}) C_L + 10 \text{ ns}$	$t_{TLH}$	5.0	—	180	360	ns
		10	—	90	180	
		15	—	65	130	
Output Fall Time $t_{TTHL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ $t_{TTHL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ $t_{TTHL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$	$t_{TTHL}$	5.0	—	100	200	ns
		10	—	50	100	
		15	—	40	80	
Propagation Delay Time $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 30 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 22 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.50 \text{ ns/pF}) C_L + 15 \text{ ns}$	$t_{PLH}, t_{PHL}$	5.0	—	115	230	ns
		10	—	55	110	
		15	—	40	80	

\*The formulas given are for the typical characteristics only at  $25^\circ\text{C}$ .

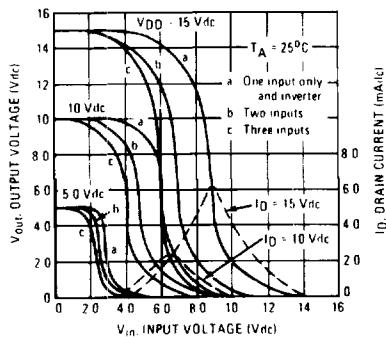
#Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

**FIGURE 1 – SWITCHING TIME TEST CIRCUIT AND WAVEFORMS**



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**FIGURE 2 – TYPICAL VOLTAGE AND CURRENT TRANSFER CHARACTERISTICS**



**FIGURE 3 – TYPICAL VOLTAGE TRANSFER CHARACTERISTICS versus TEMPERATURE**

